

IN THE CLAIMS:

Please amend the claims as follows:

1-51. (Canceled)

52. (Currently Amended) A socket contact formation process for forming a plurality of socket contacts in a substrate, the plurality of socket contacts having a spacing therebetween for mating with the contacts of an IC chip for use in the testing thereof, comprising:
forming a contact head from a conductive material as at least one member of a socket contact having at least two members forming portions thereof, the contact head for contacting one of the contacts of the IC chip for use in the testing thereof;
forming a contact body from a doped semiconductive material configured to be electrically conductive as a member of a socket contact having at least two members forming portions thereof, the contact body formed from a doped semiconductive material for use in the testing of the IC chip; and
joining said contact head and said contact body forming a socket contact having at least two members forming portions thereof, the joined contact head and the contact body having at least a portion of the contact head contacting at least a portion of a contact of the IC chip during the testing thereof.

53. (Currently Amended) The process in claim 52, wherein:
said forming a contact head comprises stamping a metal element as at least one member of a socket contact having at least two members forming portions thereof;
said forming a contact body comprises etching silicon having at least a portion thereof doped to be electrically conductive as at least one member of a socket contact having at least two members forming portions thereof; and
said joining said contact head and said contact body further comprises adhering said contact head onto said contact body forming a socket contact having at least two members forming portions thereof.

54. (Currently Amended) The process in claim 52, wherein said joining said contact head and said contact body further comprises depositing a metal over a doped silicon surface for a socket contact having at least two members forming portions thereof.

55-62. (Canceled)